

## 1.Description

The IRLML5103TR uses advanced trench technology to provide excellent  $R_{DS(on)}$  with low gate charge. This device is suitable for use as a load switch or in PWM applications.

## 2.2Features

- Generation VTechnology
- UltraLowOn-Resistance
- P-Channel MOSFET
- RoHS CompliantHalogen-Free

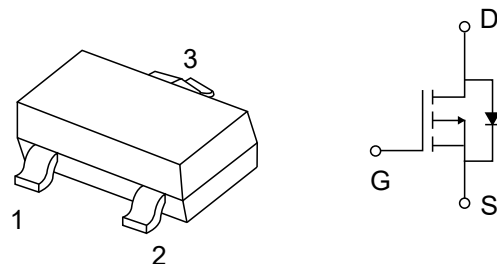
## 2.1Features

- $V_{DS(V)}=-30V$
- $R_{DS(on)}<600m\Omega(V_{GS}=-10V)$
- $R_{DS(on)}<1000m\Omega(V_{GS}=-4.5V)$

## 4.Pinning information

| Pin | Symbol | Description |
|-----|--------|-------------|
| 1   | G      | GATE        |
| 2   | S      | SOURCE      |
| 3   | D      | DRAIN       |

### SOT-23



## 5.Maximum ratings ( $T_A=25^{\circ}C$ unless otherwise noted)

| Parameter                                 |                   | Symbol         | Value      | Units           |
|-------------------------------------------|-------------------|----------------|------------|-----------------|
| Continuous Drain Current, $V_{GS}$ @ -10V | $T_A=25^{\circ}C$ | $I_D$          | -0.76      | A               |
| Continuous Drain Current, $V_{GS}$ @ -10V | $T_A=70^{\circ}C$ |                | -0.61      |                 |
| Pulsed Drain Current ①                    |                   | $I_{DM}$       | -4.8       |                 |
| Power Dissipation                         | $T_A=25^{\circ}C$ | $P_D$          | 540        | mW              |
| Linear Derating Factor                    |                   |                | 4.3        | mW/ $^{\circ}C$ |
| Gate-to-Source Voltage                    |                   | $V_{GS}$       | $\pm 20$   | V               |
| Peak diode Recovery $dv/dt$ ②             |                   | $dv/dt$        | -5         | V/ns            |
| Junction and Storage Temperature Range    |                   | $T_J, T_{STG}$ | -55 to 150 | $^{\circ}C$     |



## 6. Thermal resistance rating

| Parameter                     | Symbol          | Typ | Max | Units |
|-------------------------------|-----------------|-----|-----|-------|
| Maximum Junction-to-Ambient ④ | $R_{\theta JA}$ |     | 230 | °C/W  |

## 7. Electrical Characteristics $T_J=25^{\circ}\text{C}$

| Parameter                            | Symbol                          | Conditions                                                                                     | Min  | Typ   | Max  | Units |
|--------------------------------------|---------------------------------|------------------------------------------------------------------------------------------------|------|-------|------|-------|
| Drain-Source Breakdown Voltage       | $V_{(BR)DSS}$                   | $I_D=-250\mu\text{A}$ , $V_{GS}=0\text{V}$                                                     | -30  |       |      | V     |
| Breakdown Voltage Temp. Coefficient  | $\Delta V_{(BR)DSS}/\Delta T_J$ | $I_D=-1\text{mA}$ , Reference to $25^{\circ}\text{C}$                                          |      | 0.029 |      | V/°C  |
| Static Drain-to-Source On-Resistance | $R_{DS(ON)}$                    | $V_{GS}=-10\text{V}$ , $I_D=-0.6\text{A}$ ③                                                    |      |       | 600  | mΩ    |
|                                      |                                 | $V_{GS}=-4.5\text{V}$ , $I_D=-0.3\text{A}$ ③                                                   |      |       | 1000 |       |
| Gate Threshold Voltage               | $V_{GS(th)}$                    | $V_{DS}=V_{GS}$ , $I_D=-250\mu\text{A}$                                                        | -1   |       |      | V     |
| Forward Transconductance             | $g_{fs}$                        | $V_{DS}=-10\text{V}$ , $I_D=-0.3\text{A}$                                                      | 0.44 |       |      | S     |
| Drain-to-Source Leakage Current      | $I_{DSS}$                       | $V_{DS}=-24\text{V}$ , $V_{GS}=0\text{V}$                                                      |      |       | -1   | μA    |
|                                      |                                 | $V_{DS}=-24\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=125^{\circ}\text{C}$                          |      |       | -25  |       |
| Gate-to-Source Forward Leakage       | $I_{GSS}$                       | $V_{GS}=-20\text{V}$                                                                           |      |       | -100 | nA    |
| Gate-to-Source Reverse Leakage       |                                 | $V_{GS}=20\text{V}$                                                                            |      |       | 100  |       |
| Total Gate Charge                    | $Q_g$                           | $I_D=-0.6\text{A}$<br>$V_{DS}=-24\text{V}$<br>$V_{GS}=-10\text{V}$ , See Fig.6 and 9 ③         |      | 3.4   | 5.1  | nC    |
| Gate-to-Source Charge                | $Q_{gs}$                        |                                                                                                |      | 0.52  | 0.78 |       |
| Gate-to-Drain ("Miller") Charge      | $Q_{gd}$                        |                                                                                                |      | 1.1   | 1.7  |       |
| Turn-On Delay Time                   | $t_{D(on)}$                     | $V_{DD}=-15\text{V}$<br>$I_D=-0.6\text{A}$<br>$R_G=6.2\Omega$<br>$R_D=25\Omega$ , See Fig.10 ③ |      | 10    |      | ns    |
| Rise Time                            | $t_r$                           |                                                                                                |      | 8.2   |      |       |
| Turn-Off Delay Time                  | $t_{D(off)}$                    |                                                                                                |      | 23    |      |       |
| Fall Time                            | $t_f$                           |                                                                                                |      | 16    |      |       |
| Input Capacitance                    | $C_{iss}$                       | $V_{GS}=0\text{V}$<br>$V_{DS}=-25\text{V}$<br>$f=1\text{MHz}$ , See Fig.5                      |      | 75    |      | pF    |
| Output Capacitance                   | $C_{oss}$                       |                                                                                                |      | 37    |      |       |
| Reverse Transfer Capacitance         | $C_{rss}$                       |                                                                                                |      | 18    |      |       |



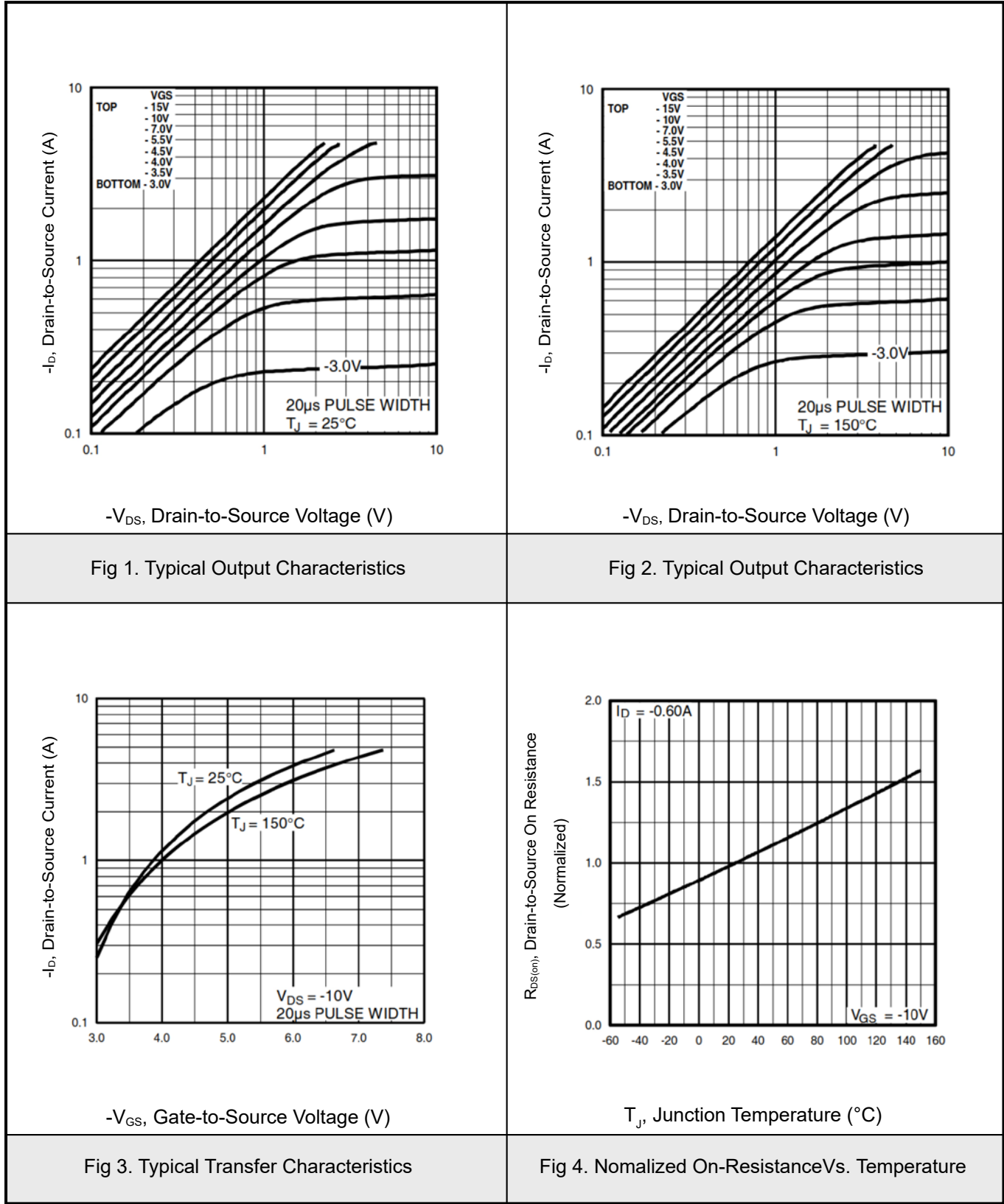
| Source-Drain Ratings and Characteristics  |          |                                                                                                                                                   |  |    |       |    |
|-------------------------------------------|----------|---------------------------------------------------------------------------------------------------------------------------------------------------|--|----|-------|----|
| Continuous Source Current<br>(Body Diode) | $I_S$    | MOSFET symbol<br>showing the<br>integral reverse<br>p-n junction diode.                                                                           |  |    | -0.54 | A  |
| Pulsed Source Current<br>(Body Diode) ①   | $I_{SM}$ |                                                                                                                                                   |  |    | -4.8  |    |
| Diode Forward Voltage                     | $V_{SD}$ | $T_J=25^{\circ}\text{C}, I_S=-0.6\text{A}, V_{GS}=0\text{V}$ ③<br>$T_J=25^{\circ}\text{C}, I_F=-0.6\text{A}$<br>$di/dt=100\text{A}/\mu\text{s}$ ③ |  |    | -1.2  | V  |
| Reverse Recovery Time                     | $t_{rr}$ |                                                                                                                                                   |  | 26 | 39    | ns |
| Reverse Recovery Charge                   | $Q_{rr}$ |                                                                                                                                                   |  | 20 | 30    | nC |

## Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature. ( See fig.11 )
- ②  $I_{SD} \leq -0.6\text{A}$ ,  $di/dt \leq 110\text{A}/\mu\text{s}$ ,  $V_{DD} \leq V_{(BR)DSS}$ ,  $T_J \leq 150^{\circ}\text{C}$
- ③ Pulse width  $\leq 300\mu\text{s}$ ; duty cycle  $\leq 2\%$ .
- ④ Surface mounted on FR-4 board,  $t \leq 5\text{sec}$ .

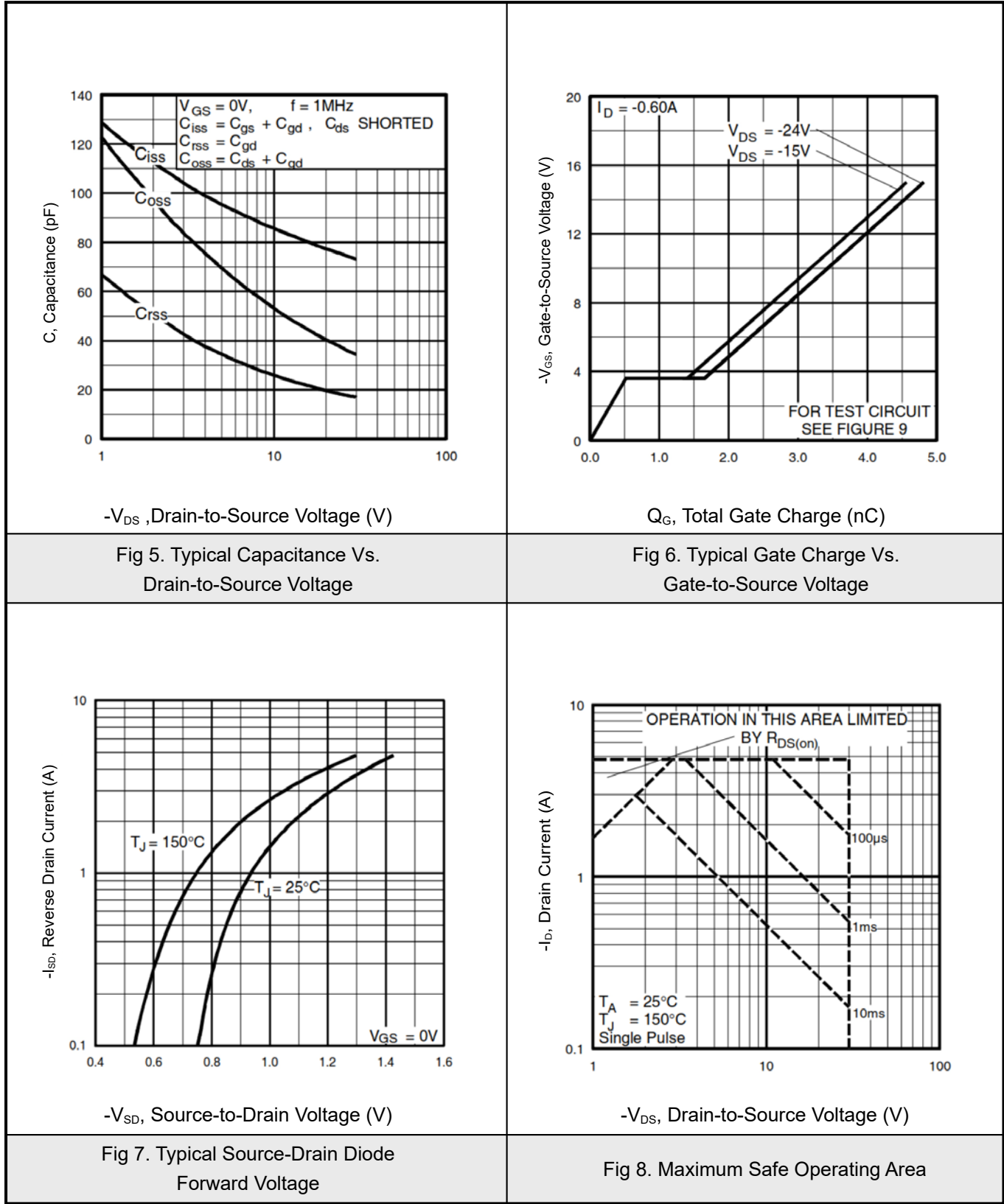


8.1Typical Characteristics





8.2Typical Characteristics





### 8.3 Typical Characteristics

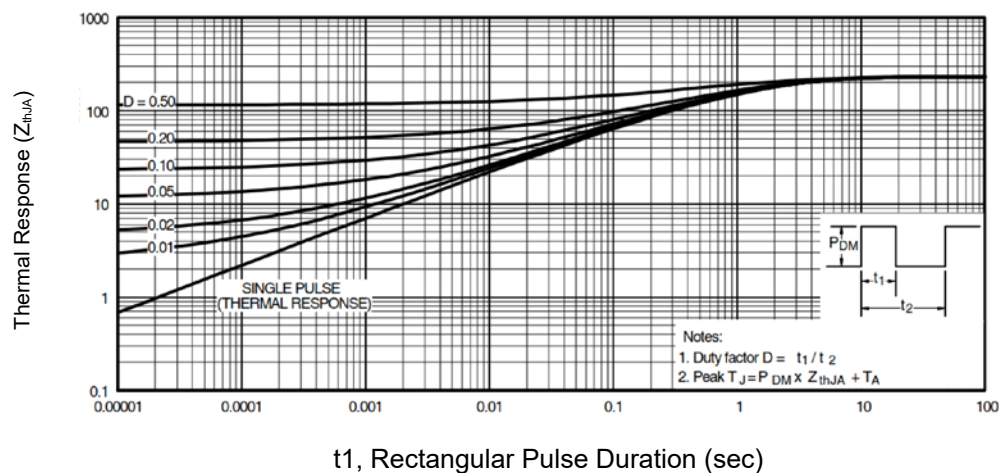


Figure 9. Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



## 8.4 Typical Characteristics

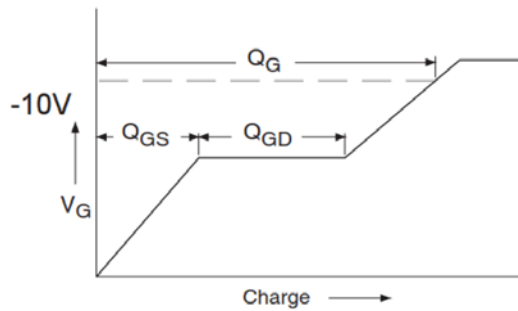


Fig 10a. Basic Gate Charge Waveform

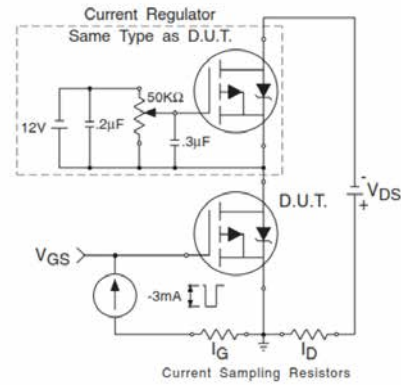


Fig 10a. Switching Time Test Circuit

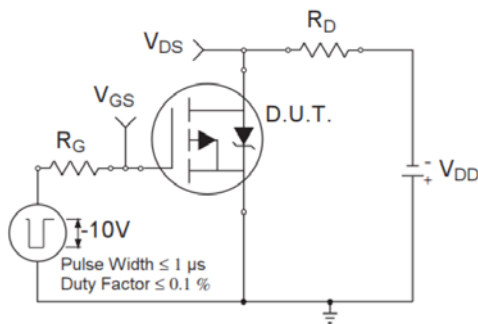


Fig 11a. Gate Charge Test Circuit

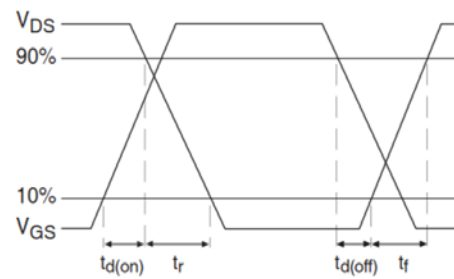
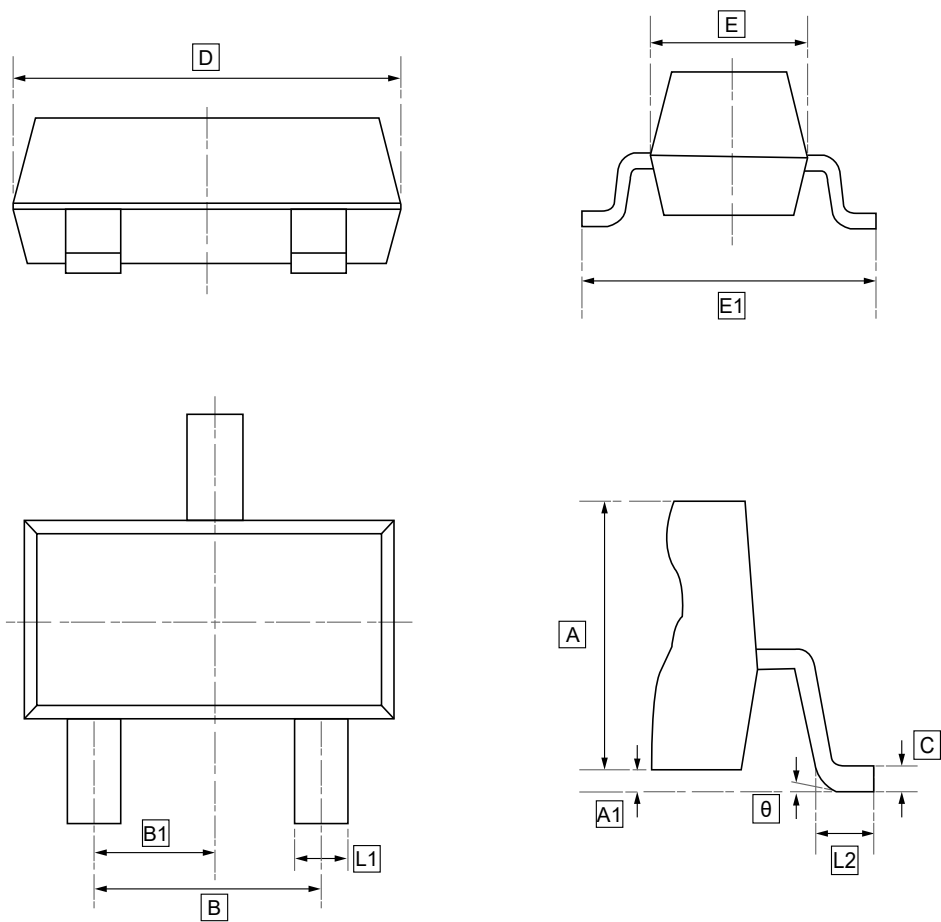


Fig 11b. Switching Time Waveforms



9.SOT-23 Package Outline Dimensions

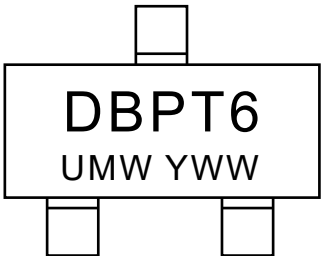


DIMENSIONS (mm are the original dimensions)

| Symbol | A     | A1    | L1    | L2    | C     | D     | E     | E1    | B     | B1    | θ  |
|--------|-------|-------|-------|-------|-------|-------|-------|-------|-------|-------|----|
| Min    | 1.050 | 0.000 | 0.300 | 0.350 | 0.100 | 2.820 | 1.500 | 2.700 | 1.800 | 0.950 | 0° |
| Max    | 1.150 | 0.100 | 0.500 | 0.550 | 0.200 | 3.020 | 1.700 | 2.900 | 2.000 | TYP   | 8° |



10.Ordering information



YWW: Batch Code

| Order Code      | Package | Base QTY | Delivery Mode |
|-----------------|---------|----------|---------------|
| UMW IRLML5103TR | SOT-23  | 3000     | Tape and reel |



## 11.Disclaimer

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